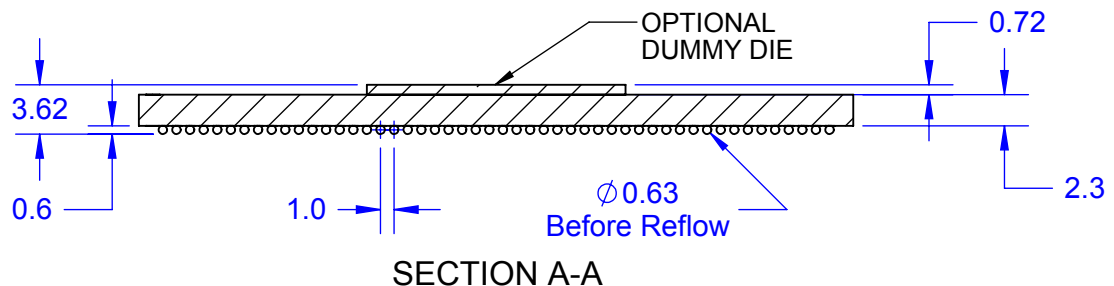
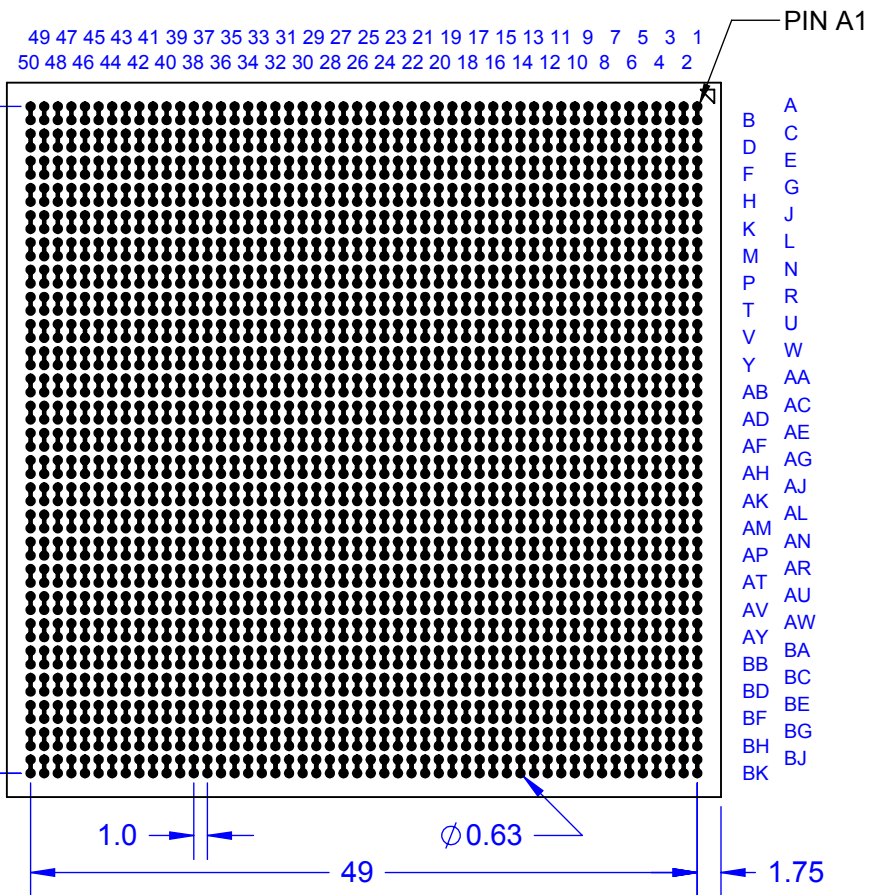
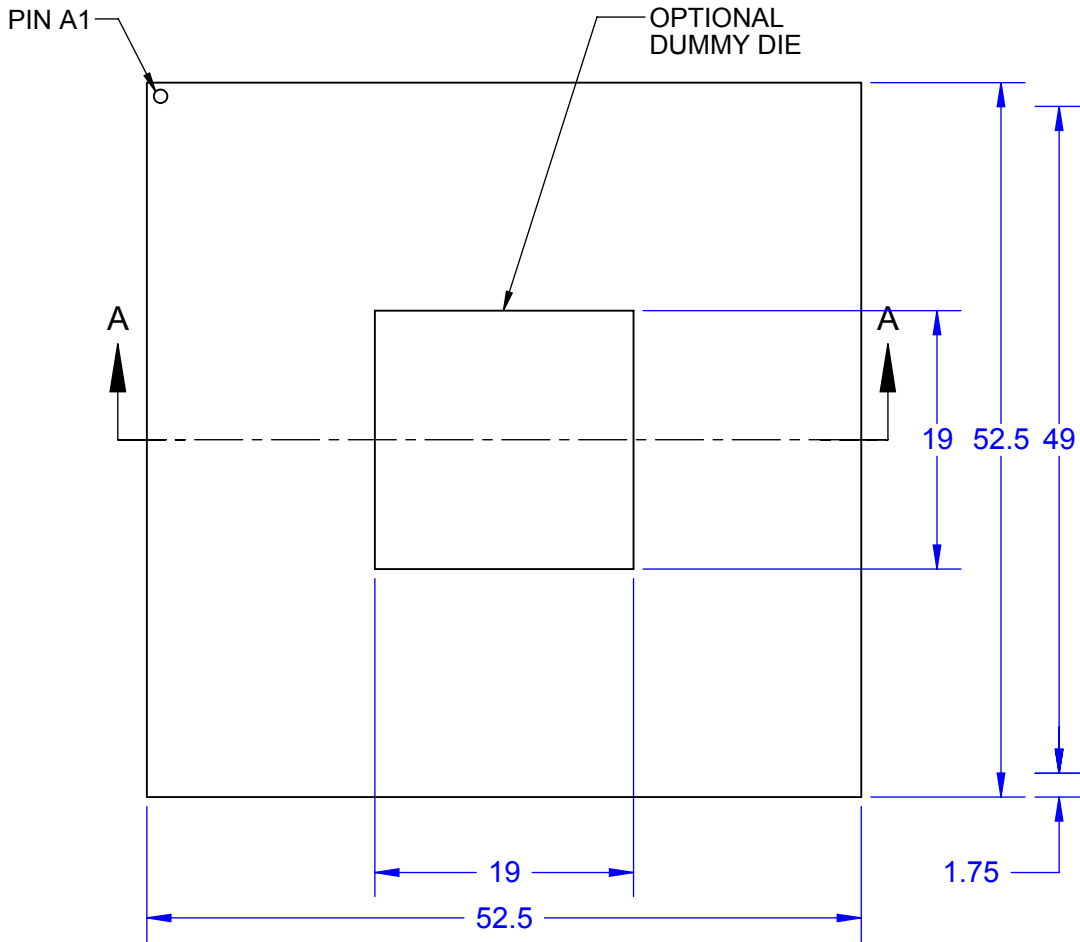


TOP VIEW

BALL VIEW



Notes: (Unless Otherwise Specified).

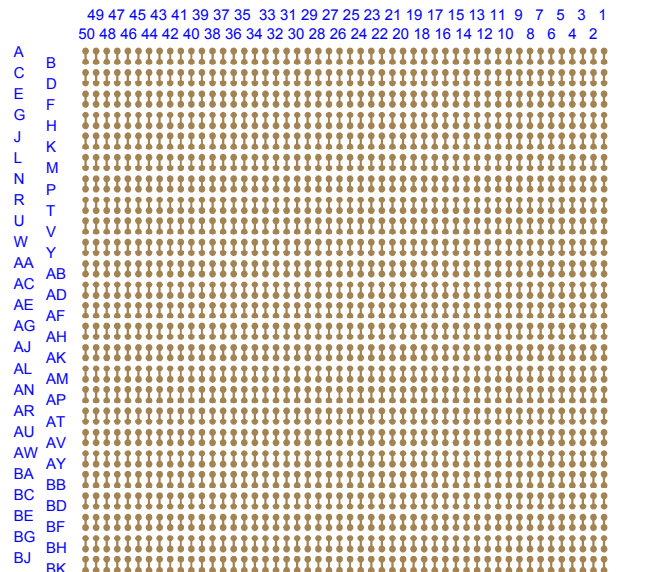
- 1) ALL DIMENSIONS ARE IN MM.
- 2) SOLDER BALL ALLOY: SEE PART NUMBER TABLE.
- 3) BALL DIAMETER (BEFORE REFLOW): 0.635mm (25 MIL).
- 4) SOLDER MASK DEFINED PAD OPENING: 0.508mm (20 MIL).
- 5) PAD Cu DIAMETER: 0.635mm (25 MIL).
- 6) SUBSTRATE MATERIAL: FR4 (ALTERNATE BT or Polyimide).
- 7) DUMMY DIE IS OPTIONAL.
- 8) DAISY CHAIN PATTERN (SEE PAGE 2).
- 9) MSL-3 RECOMMENDED BAKING 24 HOURS @ 125°C TO REMOVE MOISTURE PRIOR SOLDERING TO PC BOARD.

PART NUMBER TABLE

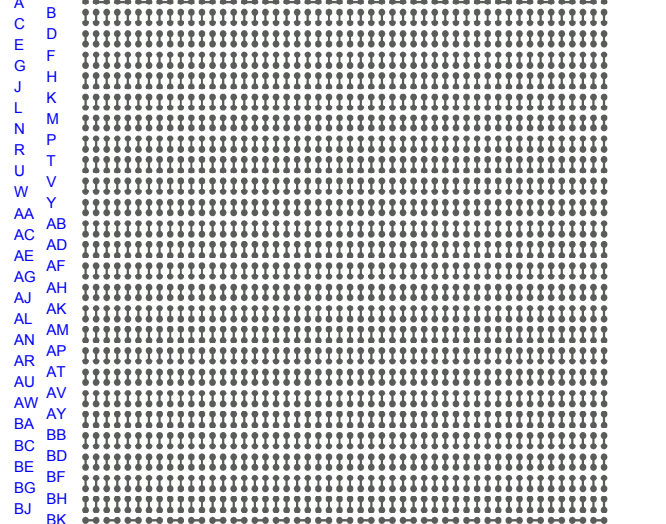
PART NUMBER	BALL ALLOY	Pb-Free	RoHS	Si DIE
LBGA2500T1.0C-DC508D	Sn96.5/Ag3.0/Cu0.5	YES	YES	YES
LBGA2500T1.0-DC508D	Sn63/Pb37	NO	NO	YES

APPROVALS	DATE	TopLine®			
DRAWN T. Au	09/20/13				
ENG M. Hart	09/20/13	TITLE		LBGA2500T1.0-DC508D DAISY CHAIN DUMMY	
MFG		SCALE	SIZE	DRAWING NO.	REV
QA		1.8:1	A	515081	A
CUST		DO NOT SCALE DRAWING			SHEET 1 OF 2
REVISED					

BALL VIEW

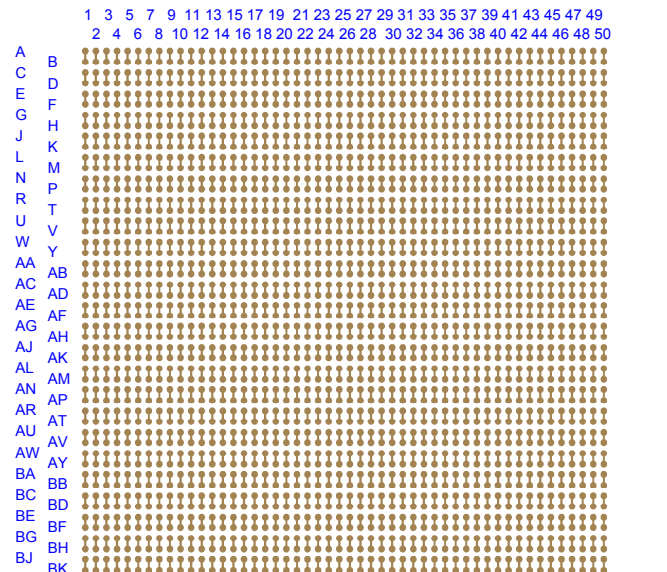


T+ 1 3 5 7 9 11 13 15 17 19 21 23 25 27 29 31 33 35 37 39 41 43 45 47 49 T-
 2 4 6 8 10 12 14 16 18 20 22 24 26 28 30 32 34 36 38 40 42 44 46 48 50

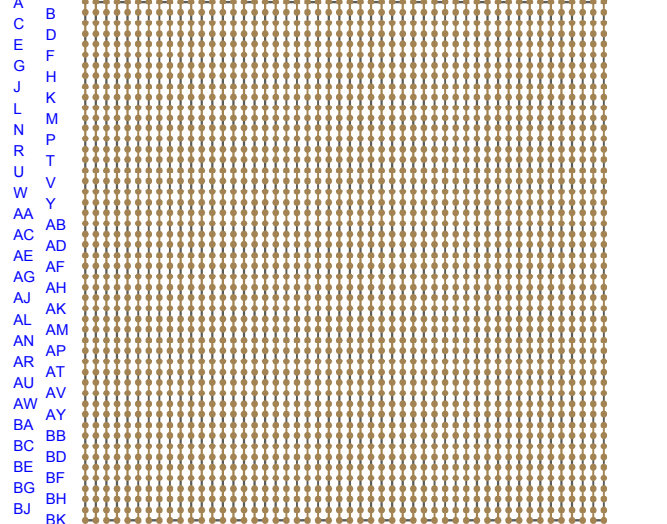


TEST VEHICLE BOARD

BOTTOM SIDE (TOP X-RAY VIEW)



T+ 1 3 5 7 9 11 13 15 17 19 21 23 25 27 29 31 33 35 37 39 41 43 45 47 49 T-
 2 4 6 8 10 12 14 16 18 20 22 24 26 28 30 32 34 36 38 40 42 44 46 48 50



AFTER MOUNTING

- Notes:
- 1) PCB BOARD DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE. DESIGNERS SHOULD USE THEIR OWN EXPERIENCE WHEN DESIGNING PCB.
 - 2) PCB Cu BALL PAD DIAMETER 0.635mm (25 MIL).
 - 3) PCB DAISY CHAIN TRACING LINE WIDTH 0.203mm (8 MIL).
 - 4) SMD (SOLDER MASK DEFINED) PAD OPENING: 0.508mm (20 MIL).

TopLine®			
TITLE		LBGA2500T1.0-DC508D DAISY CHAIN DUMMY	
SCALE	SIZE	DRAWING NO.	REV
1.4:1	A	515081	A
DO NOT SCALE DRAWING			SHEET 2 OF 2